

### Side View LEDs 57-11-BFT-HBBABBF9E-BT8-AM



#### Features

#### Lead (Pb) Free Product - RoHS Compliant

- P-LCC-4 package.
- Colored diffused resin.
- Wide viewing angle 120°.
- Inner reflector and white package.
- Qualification according to AEC-Q101 rev C.
- Precondition: Bases on JEDEC J-STD 020D Level 3.
- Automotive reflow profile (IR reflow or wave soldering)

#### Applications

- Automotive backlighting or indicator: Interior and exterior lighting, Dashboard, switch, reading lamp, audio and video equipments...etc.
- Backlight: LCD, switches, symbol, mobile phone and illuminated advertising.
- Display for indoor and outdoor application.
- Ideal for coupling into light guides.
- Substitution of traditional light.
- General applications.
- Optical indicator.

## Device Selection Guide

Chip Materials	Emitted Color	Resin Color
InGaN / SiC	White	Yellowish

## Absolute Maximum Ratings (Ta=25°C)

Parameter	Symbol	Rating	Unit
Forward Current	$I_F$	30	mA
Peak Forward Current (Duty 1/10 @1KHz)	$I_{FP}$	100	mA
Power Dissipation	$P_d$	110	mW
Junction Temperature	$T_j$	125	°C
Operating Temperature	$T_{opr}$	-40 ~ +100	°C
Storage Temperature	$T_{stg}$	-40 ~ +110	°C
Thermal Resistance	$R_{th\ J-A}$	500	K/W
	$R_{th\ J-S}$	300	K/W
ESD (Classification acc. AEC Q101)	$ESD_{HBM}$	2000	V
	$ESD_{MM}$	200	V
Soldering Temperature	$T_{sol}$	Reflow Soldering : 260 °C for 30 sec. Hand Soldering : 350 °C for 3 sec.	

## Electro-Optical Characteristics (Ta=25°C)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Condition
Luminous Intensity	$I_v$	1800	---	2800	mcd	$I_F=20mA$
Viewing Angle	$2\theta_{1/2}$	---	120	---	deg	
Forward Voltage	$V_F$	2.8	---	3.5	V	

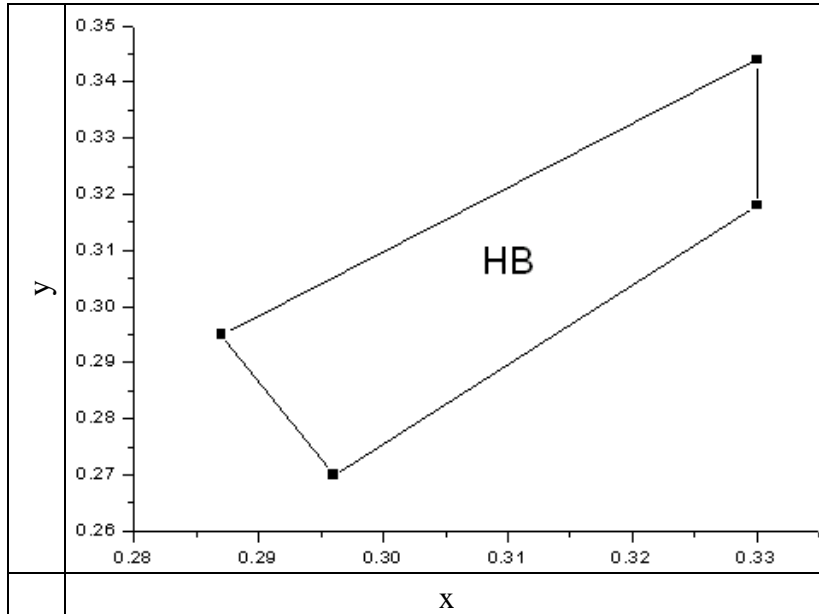
Note:

1. Tolerance of Luminous Intensity:  $\pm 11\%$
2. Tolerance of Chromaticity Coordinates is  $\pm 0.01$
3. Tolerance of Forward Voltage:  $\pm 0.1V$

### Bin Range of Luminous Intensity

Bin Code	Min.	Max.	Unit	Condition
BA	1800	2240	mcd	$I_F = 20\text{mA}$
BB	2240	2800		

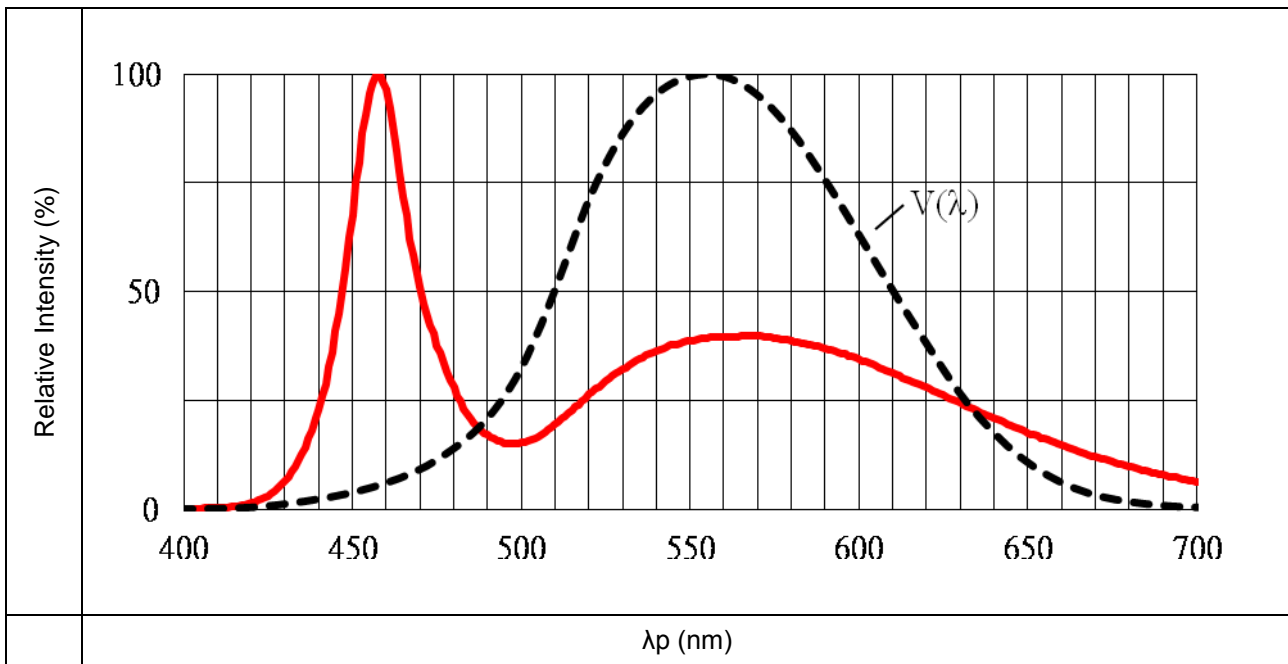
### The C.I.E. 1931 Chromaticity Diagram



### Bin Range of Chromaticity Coordinates Specifications

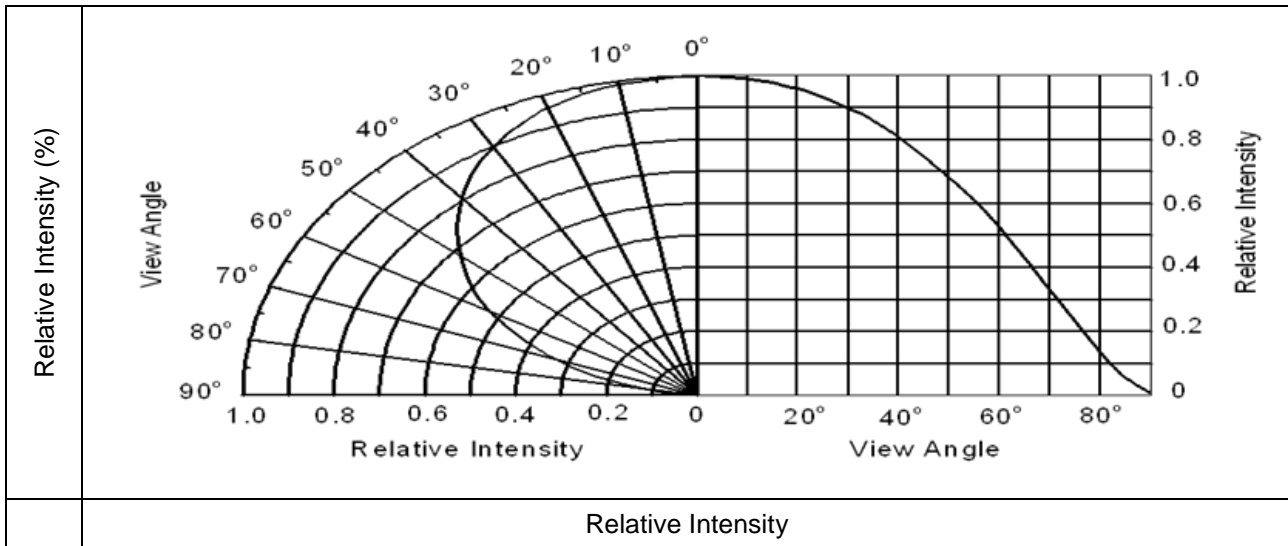
Group	Bin Code	CIE_x	CIE_y	Condition
HB	HB	0.296	0.270	$I_F = 20\text{mA}$
		0.287	0.295	
		0.330	0.344	
		0.330	0.318	

**Typical Electro-Optical Characteristics Curves(Ta=25°C)**  
**Typical Curve of Spectral Distribution**

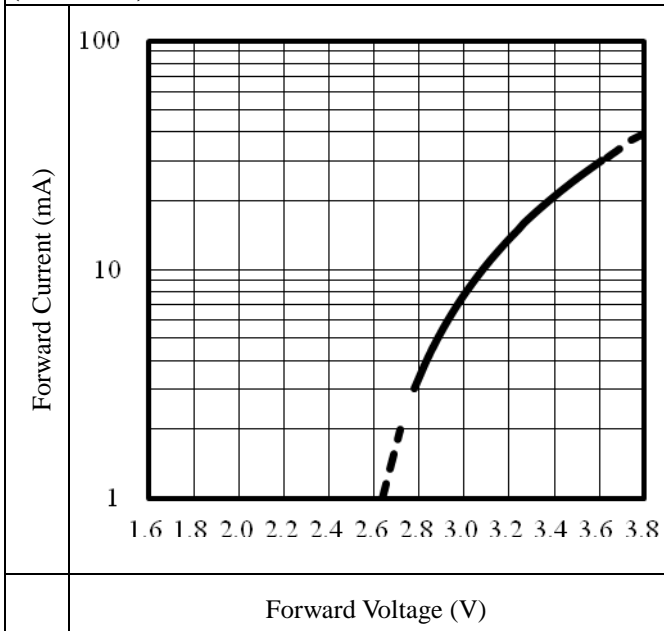


Note:  $V(\lambda)$ =Standard eye response curve;

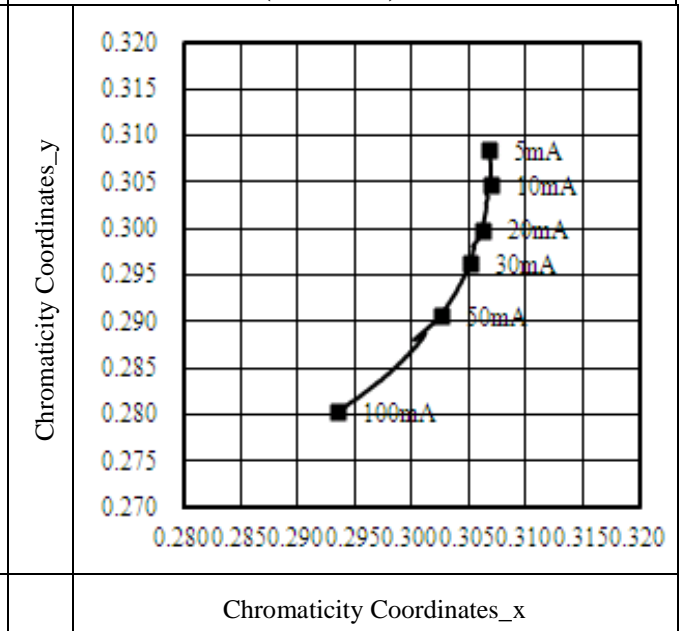
**Diagram Characteristics of Radiation**



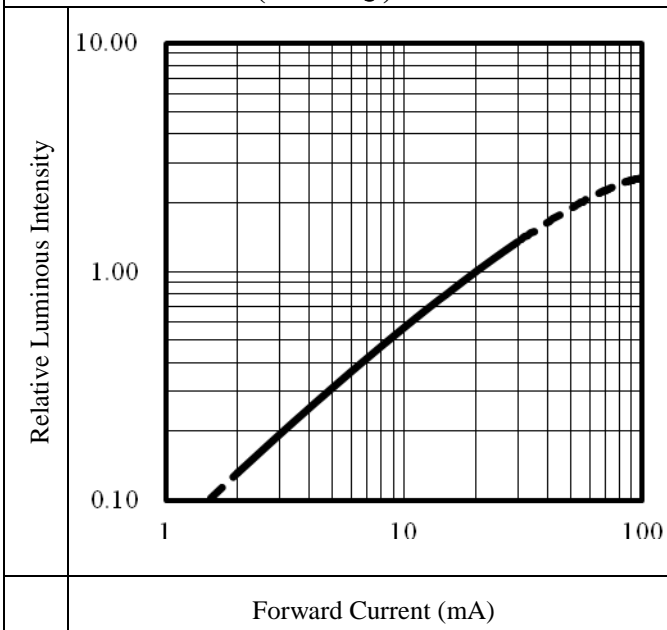
**Forward Current vs. Forward Voltage  
(Ta=25°C)**



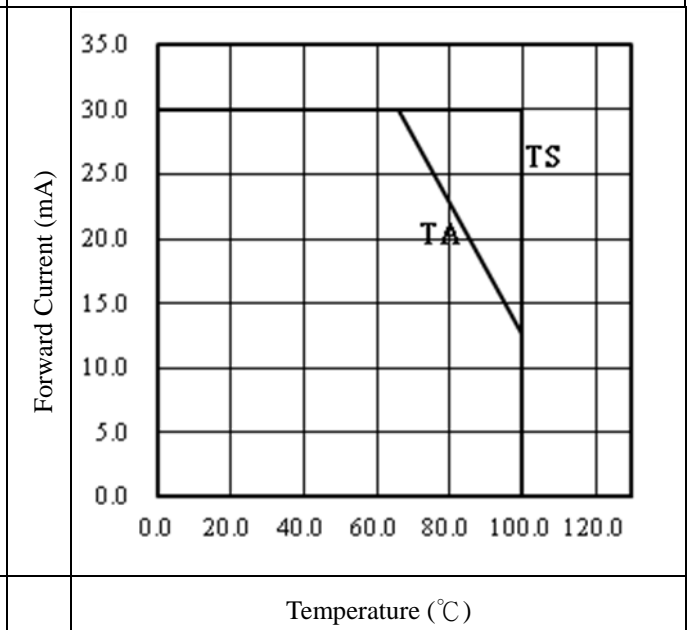
**Chromaticity Coordinates vs.  
Forward Current (Ta=25°C)**



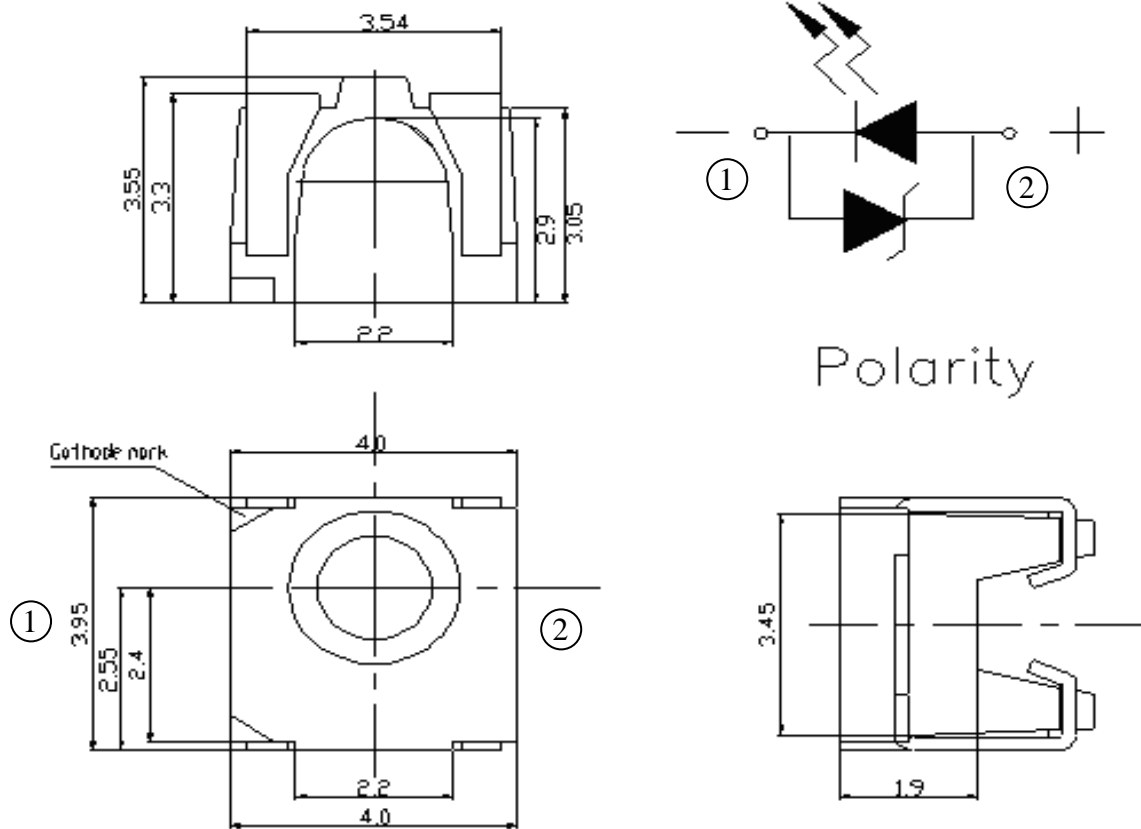
**Relative Luminous Intensity vs.  
Forward Current (Ta=25°C)**



**Max. Permissible Forwarded Current**



### Package Dimension



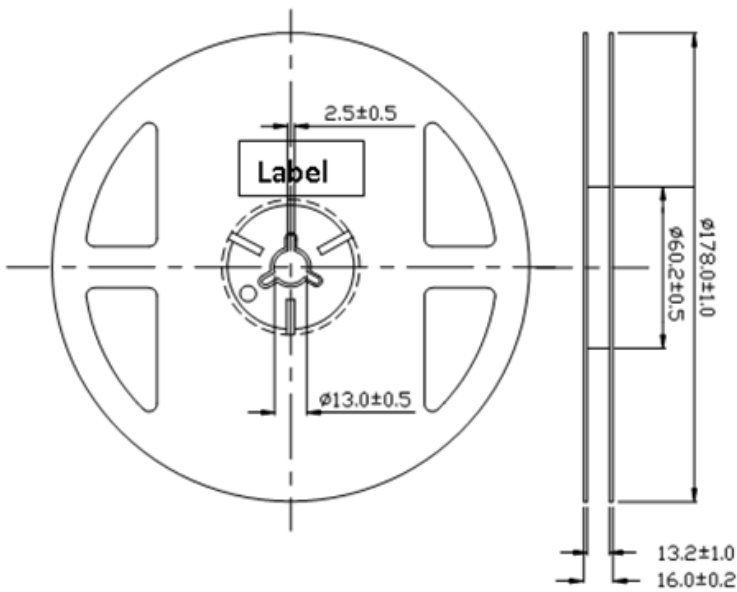
Note: Tolerances unless mentioned  $\pm 0.1$ mm. Unit = mm

### Moisture Resistant Packing Materials Label Explanation

- CPN: Customer's Product Number
- P/N: Product Number
- QTY: Packing Quantity
- CAT: Luminous Intensity Rank
- HUE: Chromaticity Coordinates Rank
- REF: Forward Voltage Rank
- LOT No: Lot Number

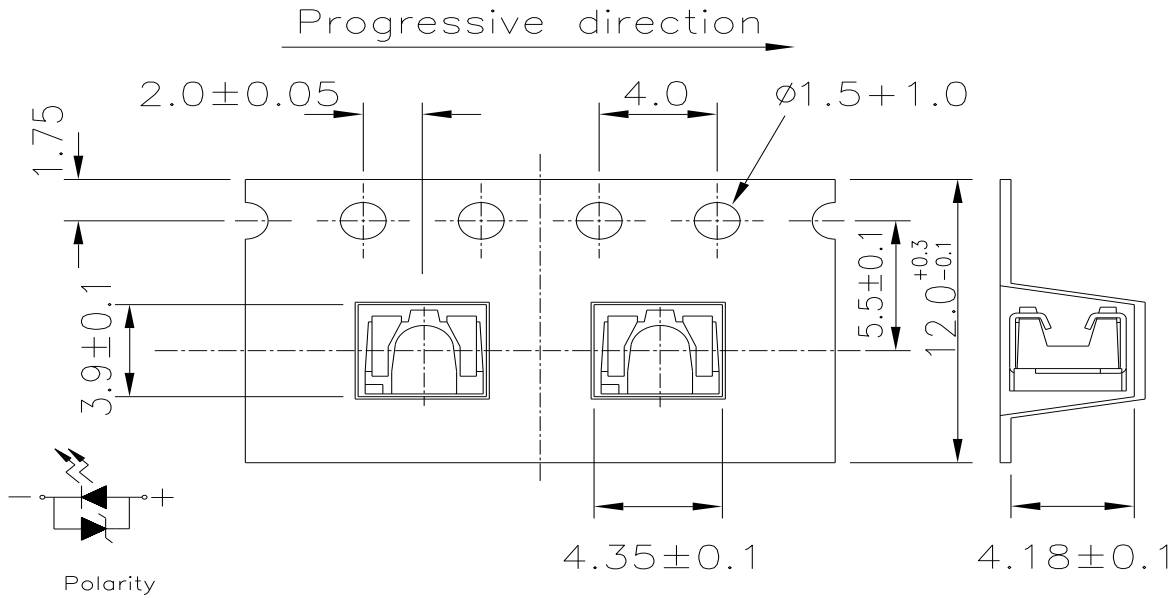


### Reel Dimensions



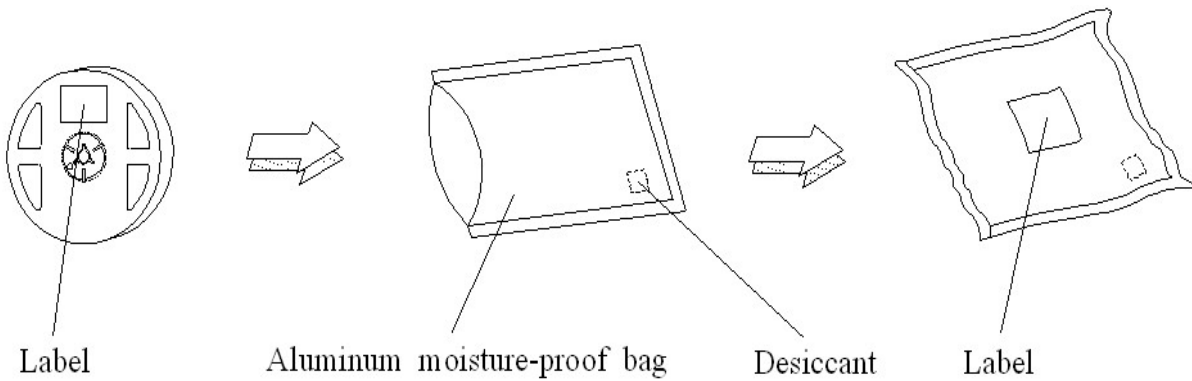
Note: Tolerances unless mentioned  $\pm 0.1$ mm. Unit = mm

**Carrier Tape Dimensions: Loaded Quantity 500 pcs Per Reel**



- Note:
1. Tolerances unless mentioned  $\pm 0.1$ mm. Unit = mm
  2. Minimum packing amount is 250/500 pcs per reel

**Moisture Resistant Packing Process**



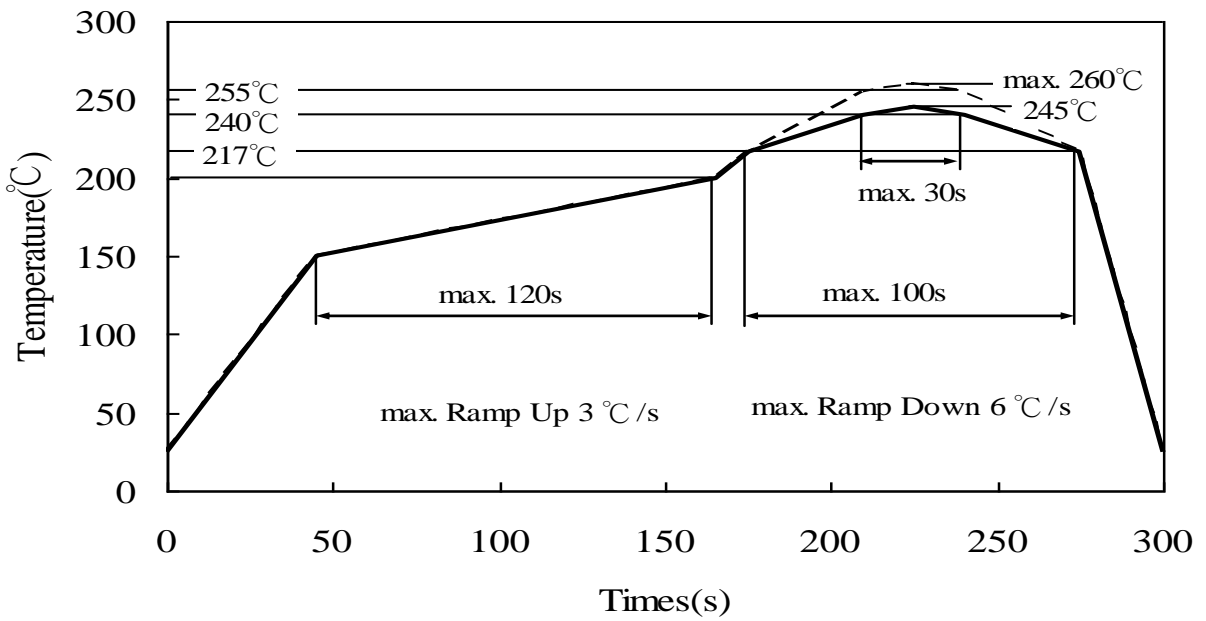
Note: Tolerances unless mentioned  $\pm 0.1$ mm. Unit = mm



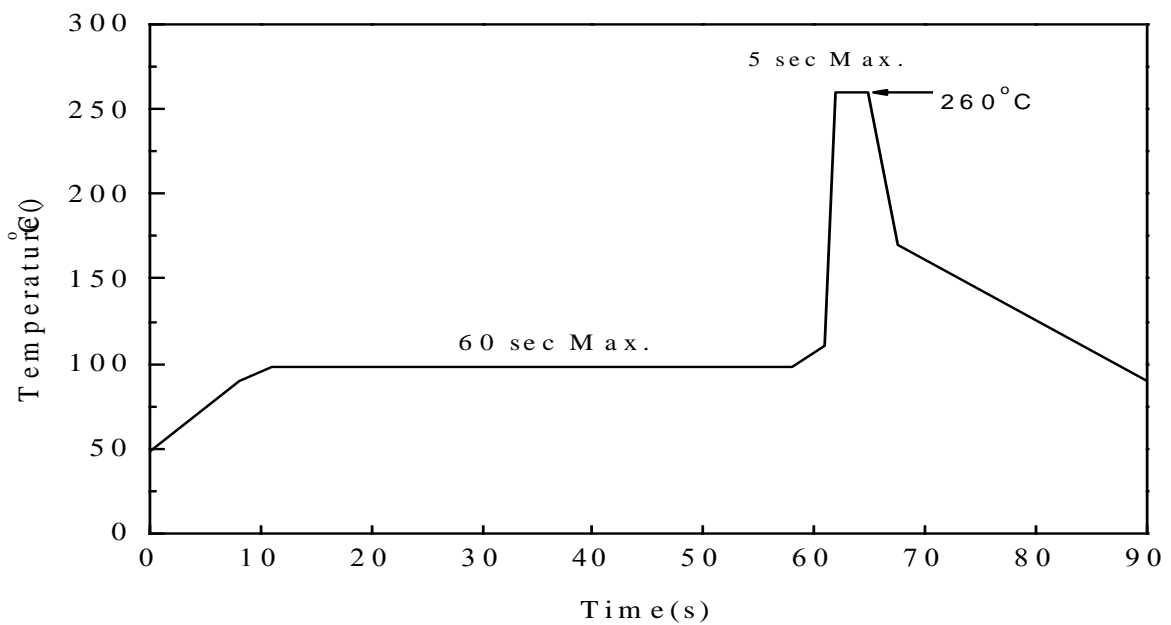
Precautions for Use

1. Soldering Condition (Reference: IPC/JEDEC J-STD-020D)

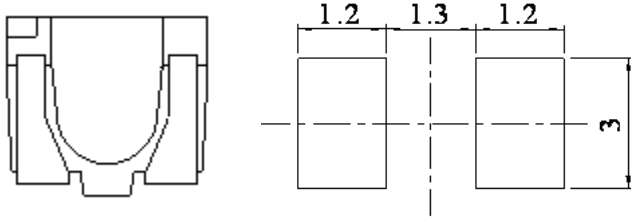
a. IR reflow



b. Wave soldering reflow



### (B) Recommend soldering pad



Note: Tolerances unless mentioned  $\pm 0.1$ mm. Unit = mm

## 2. Current limiting

A resistor should be used to limit current spikes that can be caused by voltage fluctuations. Otherwise damage could occur.

## 3. Storage

3.1 Moisture proof bag should only be opened immediately prior to usage.

3.2 Environment should be less than  $30^{\circ}\text{C}$  and 60% RH when moisture proof bag is opened.

3.3 After opening the package MSL Conditions stated on page 1 of this spec should not be exceeded.

3.4 If the moisture sensitivity card indicates higher than acceptable moisture, the component should be baked at min.  $60^{\circ}\text{deg}$   $\pm 5^{\circ}\text{deg}$  for 24 hours.

## 4. Iron Soldering

Hand soldering is not recommended for regular production. These guidelines are for rework only. Soldering iron tip should contact each terminal no more than 3 sec at  $350^{\circ}\text{C}$ , using soldering iron with nominal power less than 25W. Allow min. 2 sec. between soldering intervals.

## 5. Usage

Do not exceed the values given in this specification.

## Application Restrictions

High reliability applications such as military/aerospace, automotive safety/security systems, and medical equipment may require different product. If you have any concerns, please contact Everlight before using this product in your application. This specification guarantees the quality and performance of the product as an individual component. Do not use this product beyond the specification described in this document.